MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

Meets or Exceeds the Requirements of D, N, OR NS PACKAGE (TOP VIEW) ANSI Standards EIA/TIA-422-B and **EIA/TIA-423-B and ITU Recommendations** 1B 16 VCC V.10 and V.11 1A [15 AB 3-State, TTL-Compatible Outputs 14 🛮 4A 1Y **∏** 3 **Fast Transition Times** 1.2EN **∏** 4 13 T 4Y **Operates From Single 5-V Supply** 12 3,4EN 2Y 🛮 2A 11 3Y Designed to Be Interchangeable With 2B **∏** 7 10 3A Motorola™ MC3486 9 1 3B GND

description

The MC3486 is a monolithic quadruple differential line receiver designed to meet the specifications of ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B and ITU Recommendations V.10 and V.11. The MC3486 offers four independent differential-input line receivers that have TTL-compatible outputs. The outputs utilize 3-state circuitry to provide a high-impedance state at any output when the appropriate output enable is at a low logic level.

The MC3486 is designed for optimum performance when used with the MC3487 quadruple differential line driver. It is supplied in a 16-pin package and operates from a single 5-V supply.

The MC3486 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED D	EVICES	
TA	PLASTIC SMALL OUTLINE (D, NS)	PLASTIC DIP (N)	
0°C to 70°C	MC3486D MC3486NS	MC3486N	

The D package is available taped and reeled. Add the suffix R to the device type (e.g., MC3486DR). The NS package is only available taped and reeled.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Motorola is a trademark of Motorola, Incorporated.

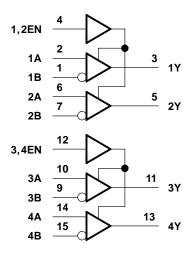


FUNCTION TABLE (each receiver)

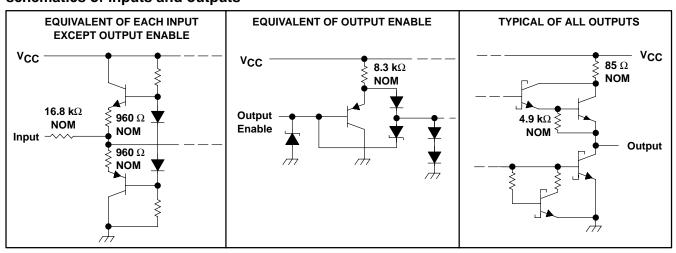
DIFFERENTIAL INPUTS A-B	ENABLE	OUTPUT Y
V _{ID} ≤ 0.2 V	Н	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	Н	?
$V_{ID} \le -0.2 V$	Н	L
Irrelevant	L	Z
Open	Н	?

H = high level, L = low level, Z = high impedance (off), ? = indeterminate

logic diagram (positive logic)



schematics of inputs and outputs





MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	8 V
Input voltage, V _I (A or B inputs)	
Differential input voltage, V _{ID} (see Note 2)	
Enable input voltage	8 V
Low-level output current, IOL	
Package thermal impedance, θ _{JA} (see Note 3): D package	
N package	67°C/W
NS package	67°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential-input voltage, are with respect to network ground terminal.
 - 2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIC	Common-mode input voltage			±7	V
VID	Differential input voltage			±6	V
VIH	High-level enable input voltage	2			V
VIL	Low-level enable input voltage			0.8	V
TA	Operating free-air temperature	0		70	°C

MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITION	s	MIN	MAX	UNIT
V _{IT+}	Differential input high-threshold voltage	$V_0 = 2.7 \text{ V}, \qquad I_0 = -0.4 \text{ mA}$			0.2	V
V_{IT-}	Differential input low-threshold voltage	$V_{O} = 0.5 \text{ V}, \qquad I_{O} = -8 \text{ mA}$		-0.2†		V
V_{IK}	Enable-input clamp voltage	$I_I = -10 \text{ mA}$			-1.5	V
Vон	High-level output voltage	V_{ID} = 0.4 V, I_{O} = -0.4 mA, See Note 4 and Figure 1		2.7		٧
VOL	Low-level output voltage	$V_{\text{ID}} = -0.4 \text{ V}, \qquad I_{\text{O}} = 8 \text{ mA},$ See Note 4 and Figure 1			0.5	٧
1	High-impedance-state output current	$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = -3 \text{ V},$	V _O = 2.7 V		40	μΑ
loz		$V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = 3 \text{ V},$	$V_0 = 0.5 \text{ V}$		-40	
	Differential-input bias current		$V_{I} = -10 \text{ V}$		-3.25	
		V _{CC} = 0 V or 5.25 V,	$V_I = -3 V$		-1.5	mA
IВ		Other inputs at 0 V	V _I = 3 V		1.5	
			V _I = 10 V		3.25	
1	High level anable input assument	V _I = 5.25 V			100	
lιΗ	High-level enable input current	V _I = 2.7 V			20	μΑ
IլL	Low-level enable input current	V _I = -0.5 V			-100	μΑ
los	Short-circuit output current	$V_{ID} = 3 V, V_{O} = 0,$	See Note 5	-15	-100	mA
ICC	Supply current	V _{IL} = 0	•		85	mA

[†] The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

NOTES: 4. Refer to ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

5. Only one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPHL	Propagation delay time, high- to low-level output	See Figure 2		28	35	ns
tPLH	Propagation delay time, low- to high-level output	See Figure 2		27	30	ns
^t PZH	Output enable time to high level			13	30	ns
tPZL	Output enable time to low level	See Figure 3		20	30	ns
tPHZ	Output disable time from high level	See Figure 3		26	35	ns
^t PLZ	Output disable time from low level			27	35	ns



PARAMETER MEASUREMENT INFORMATION

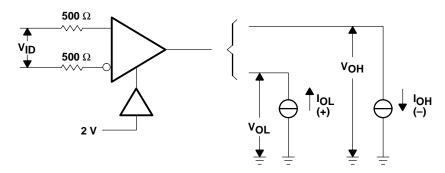
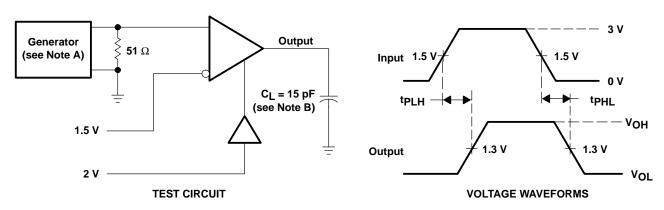


Figure 1. V_{OH}, V_{OL}

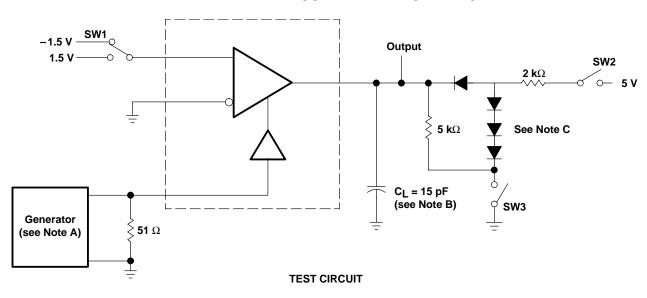


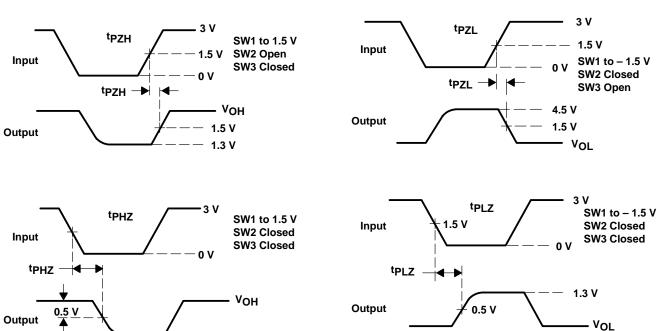
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_{f} \leq$ 6 ns, $t_{f} \leq$ 6 ns.

B. C_L includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION





NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns.

B. CL includes probe and stray capacitance.

1.3 V

C. All diodes are 1N916 or equivalent.

Figure 3. Test Circuit and Voltage Waveforms







com 18-Jul-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MC3486D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
MC3486N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC3486NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC3486NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC3486NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

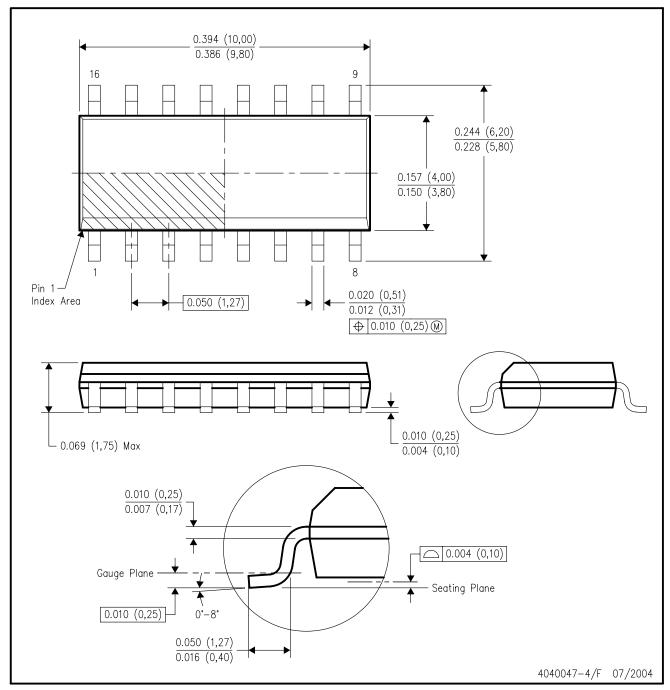


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated